FTIR 8700 HA & SOP

Below is a listing of the available SOP's & Hazard Assessments for this Equipment

Standard Operating Procedures

Title	Location	Process Area
Zeiss EVO SEM SOP	ECERF W1-040	CHARACTERIZATION
Autosorb iQ SOP	ECERF W1-040	CHARACTERIZATION
Dimension Edge AFM SOP	CME L2-112	CHARACTERIZATION
How-To Request a Dicing Blade Change	W1-060	PACKAGING
Zeiss Sigma FeSEM SOP	ECERF W1-060	CHARACTERIZATION
Branson Barrel Etcher SOP	W1-062	Plasma Etch
memsstar Vapour HF Etcher SOP	W1-062	Dry Etch
Thin Film Stress Measurement - Flexus 2320 SOP	W1-062	Characterization
Achilles PM Procedure		
Brewer Spinner and Hotplate SOP	W1-062	LITHOGRAPHY
Suss CB6L Bonder SOP	W1-062	Bonding
Oxford Estrelas ICP-RIE SOP	W1-062	PLASMA ETCH
Oxford NGP80 RIE SOP	W1-062	PLASMA ETCH
Disco DAD 321 Dicing Saw SOP	W1-060	PACKAGING
Parylene Deposition System PM Procedure		
Trion RIE SOP	W1-062	PLASMA ETCH
Trion PECVD SOP	W1-062	DEPOSITION
Interfacial Tension SOP	ECERF W1-040	Characterization
Contact Angle FTA-200 SOP	ECERF W1-040	Characterization
HowTo Put the LPCVD into a Safe State after a failure	W1-062	DEPOSITION
Zeiss Sigma FeSEM EBSD SOP	ECERF W1-060	CHARACTERIZATION
Sitek - Semitool 870-S SRD - SOP	Aisle 2	WET PROCESSING
Rigaku XRD SOP	ECERF w1-040A	CHARACTERIZATION
Parylene Deposition System SOP	W1-060	DEPOSITION
Floyd Sputtering System SOP	W1-060	DEPOSITION
Doug Sputter System SOP	W1-060	DEPOSITION
Bob Sputtering System SOP	W1-060	DEPOSITION

JEOL ARM SOP	CME L2-121	CHARACTERIZATION
Heidelberg MLA150 SOP	Clean room, W1-062B	LITHOGRAPHY
Filmetrics F50-UV SOP	W1-062	CHARACTERIZATION
Gomez E-Beam Evaporation System SOP	W1-060	DEPOSITION
Critical Point Drier SOP	W1-062	ANCILLARY
Bruker XRD D8 Discover SOP	ECERF W1-040A	CHARACTERIZATION
Autosorb Quantachrome 1MP SOP	ECERF W1-040	CHARACTERIZATION
Alcatel AMS110 ICPRIE SOP	W1-062	PLASMA ETCH
RAITH150 Two EBL System SOP	Clean room, ECERF W1-062A	LITHOGRAPHY
Photomask Cleaning Station SOP	W1-062	lithography support
PlasmaLab μEtch SOP	W1-062	Plasma Etch
Nanoscribe Photonic Professional GT SOP	W1-062, Primary lithography	LITHOGRAPHY
TPT HB16 Wire bonder SOP	Characterization Lab, ECERF W1-040	PACKAGING
Dump Rinse Controller Standard Program	W1-062	Wet Etch
Perkin Elmer Spectrophotometer SOP	W1-040	Characterization
Tescan Vega3 SEM SOP	ECERF W1-040A	Characterization
UV Ozone Bonder SOP	W1-062	PDMS
PDMS Process Area SOP	W1-060	Polymer Processing
KOH and TMAH Etch SOP	W1-062	Wet Etch
Zygo Optical Profilometer SOP	W1-040	Characterization
Xenon Difluoride (XeF2) Etch System SOP	W1-062	Dry Etch
MiniBrute Furnace SOP	W1-062	Film Growth, Deposition
Headway Resist Spinner SOP	W1-062	Lithography

Hazard Assessments

Title	Location	Process Area
EDGE AFM HA	CME L2-112	
Zeiss Versa Xradia 620 HA	CMEB L1-113	CHARACTERIZATION
Contact Angle and InterFacial Tension HA	ECERF W1-040	
Bruker XRD HA	ECERF w1-040A	CHARACTERIZATION